

Final Product Change Notification

202402014F01: NVT2008BQ Wire Conversion from Au to Cu and Roughened Leadframe

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 06, 2024 Effective date: Jun 14, 2024

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Management summary

NXP will change the wire for the bonding process of the NVT2008BQ product, from gold to copper in conjunction with a roughened leadframe, for improved reliability and manufacturing logistics. This will align the manufacturing process and flow of this product to industry standard.

Change Category

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[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware	[]Other			

PCN Overview

Description

ATBK will convert to copper wire and roughened leadframe.

Reason

Copper wire and roughened leadframe will improve overall product reliability and reduce logistics risks in production by moving the product to standard, current production materials.

Identification of Affected Products

Product identification does not change

Orderable part number for the NVT2008BQ product will transition from 12NC 9352 919 82115 to 12NC 9352 919 82471, which is currently available for immediate purchase.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Mar 15, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Apr 05, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Orderable Part Number# 1 2NC Product Type Product Upser/ption Package Outline Park Number# 1 2NC NVT20088Q.115 NVT20088Q Bidirectional voltage level vlator or MVT20088Q.115 NVT20088Q Bidirectional voltage level vlator or NVT20088Q.115 NVT20088Q Bidirectional voltage level vlator or NVT2008A Bidirectional voltage level vlator or NVT2